



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#20/F
D. EVANS
7.9.03

In re Application of:

Hawks, et al.

Serial No.: 09/638,172

Filed: August 11, 2000

For: **Method and Structure for Securing a
Mold Compound to a Printed Circuit
Board**

Art Unit: 2831

Examiner: Ngo, Hung V.

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AMENDMENT AND RESPONSE TO *ADVISORY ACTION*

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

This is in response to the *Advisory Action* dated May 30, 2003 in the above-referenced patent application. Please enter and consider the following amendments and remarks in light of the attached *Request for Continued Examination* filed under 37 CFR §1.114 in the above-identified application.

In the Claims:

Please enter the following amended claims 20 and 25:

20. (Once Amended) A structure comprising:

a printed circuit board including a die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

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said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said die, said through hole being completely filled with a mold compound during a molding process, said mold compound being selected from the group consisting of multifunctional epoxy, novolac, and biphenyl resin, said through hole being unplated, said mold compound surrounding and covering said die, wherein said mold compound is locked into said first and second layers of metal of said printed circuit board.

25. (Once Amended) A plastic laminate-based molded printed circuit board package comprising:

a printed circuit board including a semiconductor die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

F2 said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said semiconductor die, said through hole being completely filled with a mold compound during a molding process, said through hole being unplated, said mold compound surrounding and covering said semiconductor die, wherein said mold compound is locked into said first and second layers of metal of said printed circuit board.
